

ABSTRACT

The present invention provides a method and apparatus for plating a substrate to form wiring by efficiently filling a fine recess (42) formed in a semiconductor substrate (W) with plating metal without a void or contamination. The method for plating a substrate to fill a wiring recess formed in a semiconductor substrate with plating metal (43) comprises performing an electroless plating process of forming an initial layer (41) on a substrate (W), and performing an electrolytic plating process of filling the wiring recess with plating metal, while the initial layer serves as a feeding layer.